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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Gi Ho Ahn	06/27/2013
Tae Uk Kim	06/27/2013
Jung Ki Kim	06/27/2013

RECEIVING PARTY DATA

Name:	Cheil Industries Inc.
Street Address:	290 Gongdan-dong
City:	Gumi-si
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13931952

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	6250.206
NAME OF SUBMITTER:	Melissa B. Pendleton
Signature:	/Melissa B. Pendleton/
Date:	06/30/2013

Total Attachments: 3

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> PATENT REEL: 030716 FRAME: 0413

1393195

ASSIGNMENT

WHEREAS, I, Gi Ho Ahn, a Japanese citizen, with a mailing address of Cheil Industries Inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea; Tae Uk Kim, a Korean citizen, with a mailing address of Cheil Industries Inc., 332-2, Gocheondong, Uiwang-si, Gyeonggi-do, Republic of Korea; and Jung Ki kim, a Korean citizen, with a mailing address of Cheil Industries inc., 332-2, Gocheon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in Polycarbonate Resin Composition Having Excellent Chemical Resistance, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from an international application filed on November 22, 2011, under Serial No. PCT/KR2011/008930, which itself claims priority from a Korean application filed on December 30, 2010, under Serial Nb. 10-2010-0138606, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional

papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filled concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.